sealing in a package said electronic element, element placement pad, part of said first lead, and a part of said second lead by injecting a sealing resin in the die from a position on a longer side of the package, said position being offset toward one shorter side thereof;

wherein said first lead is bent in an S shape, a bending depth d therefore being at least as large as the thickness t of said first lead, and a thickness T of said resin on a non-device side of said element placement pad is smaller than said bending depth d.

15. (new) A method according to claim 14, wherein the spacing between said element placement pad and said second lead is no greater than 0.12 mm.

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16. (new) A method according to claim 14, wherein the vertical, horizontal and height outer dimensions of said sealing resin are each no greater than 1.0 mm.

17. (new) A method according to claim 14, wherein widths of inner lead parts of said first and second leads within said sealing resin are substantially uniform.

18. (new) A method according to claim 14, wherein the thickness of said electronic element is substantially the same as the thickness t of said first lead.

19. (new) A method according to claim 14, wherein a bending radius R on an outer surface of a bent part of said first lead near a bottom surface of said sealing resin is at least 0.05 mm and is no greater than the lead thickness t.

20. (new) A method according to claim 14, wherein the sealing resin contains a filler, whose particle diameter is not greater than half the bending depth d of the said first lead.